SPECIFICATION FOR YOLDAL CHIP LED

PART. NO: UBSM0603WW

YOLDAL



■ Features:

- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.

■ Descriptions:

- Much smaller than lead frame type components, enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- > Lightweight for miniature applications.

Applications:

- > Model Railroad and Auto Headlights
- Backlighting
- Indicators
- Switch and symbol
- ➤ General use

■ Benefits:

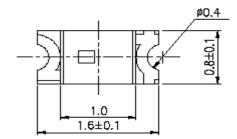
- Low Energy Consumptions
- Low Maintenance Costs
- High Application Design Flexibility
- High Reliability
- Very Competitive prices

■ Device material descriptions:

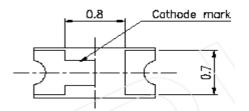
Part ID	Chip		Lens Color	
UBSM0603WW	Material	Emitted Color	Yellow	
OBSINIOUSWW	GaN	Sunny White	Diffused	

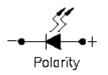
■ Package Outline Dimensions:



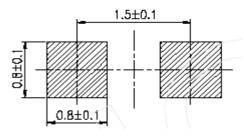








For reflow soldering (propose)



Notes: Tolerances Unless Dimensions, 0.1mm,Angles ± 0.5°, Unit: mm



Absolute maximum ratings:

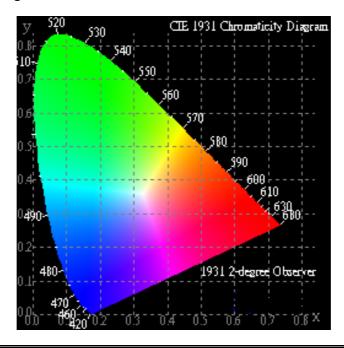
Parameter	Symbol	Rating	Unit	
Reverse Voltage	V_R	5	V	
Forward Current	I _F	20	mA	
Operating temperature	Topr	-25 ~ +80	°C	
Storage Temperature	Tstg	-30 ~ +85	°C	
Soldering temperature	Tsol	260 (for 5 Second)	°C	
Power Dissipation	Pd	80	mW	
Electrostatic Discharge*	ESD	150	V	
Peak Forward Current	1	100	mA	
(Duty 1/10 @1KHz)	I _{PF}	100		

^{*}Static Electricity Sensitive, care must be fully taken when handling this product.

Electro-Optical characteristics:

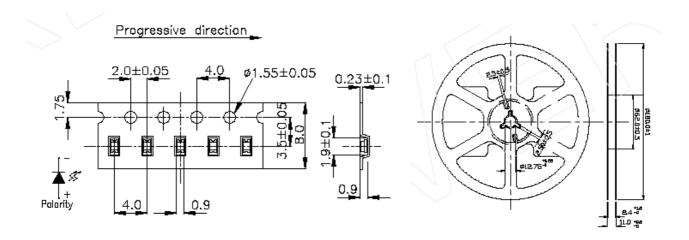
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	I_{V}		200		mcd	I _F =20 mA
Viewing angle	2 \theta 1/2		120		Deg.	I _F =20 mA
Forward Voltage	V_{F}		3.2	3.5	V	I _F =20 mA
Reverse Current	I_R			50	uA	$V_R=5V$
Chromaticity*	X		0.440			I _F =20 mA
Coordinate	Y		0.450			

*C.I.E. 1931 Chromaticity Diagram.





■ Taping Dimensions: 4000 pieces per reel.



■ Reliability Test and Condition:

Item	Test Condition	Test	Sampling	Failure	Ac/Rc
		Hour/Cycle	pcs.	Judgment	AC/RC
Reflow	Temp.: 240 °C±5°C	6 min.	30		0/1
	Min. 5 Second				0/1
	H: +85 °C, 30 min.			$I_R \ge U \times 1.0$	
Temperature Cycle	\int 5 min.	50 cycles	30	$I_V \ge L x 0.5$	0/1
	L: -55 °C, 30 Min.			$V_F \ge U x 1.2$	
	H: +100 °C, 5 min.				
Thermal Shock	∫ 10 Sec.	50 cycles	30	U: Upper	0/1
	L: -10 °C, 5 Min.			specification	
High Temperature	+100°C	1000 hrs.	30	limited	0/1
Storage	+100 C				
Low Temperature	-55 °C	1000 hrs.	30	L: Lower	0/1
Storage	-55 C			specification	
DC Operating Life	I _F =20mA	1000 hrs.	30	limited	0/1
High	+85 °C / R.H. 85%	1000 has	20		0/1
Temperature/Humidity	TOD U/K.H. 00%	1000 hrs.	30		U/ I



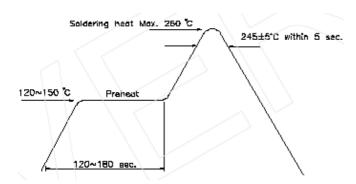
Precautions For Use

1. Over Current Proof

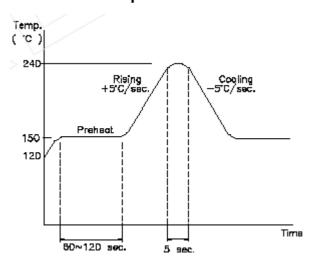
Resistors must properly applied for protection, slightly voltage shift will cause big current change, BURN OUT will happen.

- 2. Storage Time
- 2.1. The operating temperature and RH: 5 °C ~ 35 °C, RH60%.
- 2.2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccating agent. Taping life considering, strongly suggest using this products within one year from date of production.
- 2.3. Package opened more than one week in an normal atmosphere environment, before soldering, they should be treated at $60 \,^{\circ}\text{C} \pm 5 \,^{\circ}\text{C}$ for 15 hrs.
- 2.4. When the desiccant agent changed to pink, the device should be treated as condition 2.3.

Soldering Heat Reliability

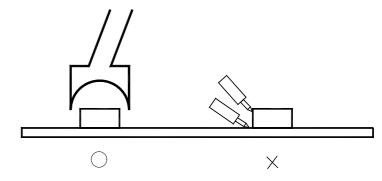


■ Reflow Temp. / Time



■ Rework

- 1. Rework must be finished within 5 sec. under 245 °C.
- 2. The head of Iron must not touch the copper foil.
- 3. Twin-head type is preferred.



Soldering Iron

Basic spec is ≤5 sec. / 260 °C. If temperature is higher, time should be shorted (+10 °C→-1 sec.). Power dissipation of Iron should be smaller than 15 W, and temperature should be controllable. Surface temperature of the device should be under than 230 °C.